

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	25	q with control and electroplat\$ with copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 14:32
L6	902	electroplat\$ with copper and replenish\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 14:32
L7	12	electroplat\$ with copper and replenish\$5 same (HCl hydrochloric) same (sulfuric sulfate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 14:47
L8	0	base adj bath and ("204" "205" "427").ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 14:47
L9	90	base adj bath and ("204" "205" "427").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 14:49
L10	2	205/101.ccls. AND ((BASE ADJ BATH) (standard adj liquid))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 14:50
L11	2	205/82.ccls. AND ((BASE ADJ BATH) (standard adj liquid))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 16:48
L12	2	205/82,101.ccls. AND ((BASE ADJ BATH) (standard adj liquid))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 16:48
L13	1	(standard adj liquid).clm. and analyz\$3.clm. and (plating electroplating).clm.	US-PGPUB	OR	ON	2006/09/08 16:49
L14	93	analyz\$3.clm. and (plating electroplating).clm.	US-PGPUB	OR	ON	2006/09/08 16:49

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L15	40	analyz\$3.clm. and (plating electroplating).clm. and concentration. clm.	US-PGPUB	OR	ON	2006/09/08 16:50
L16	30	analyz\$3.clm. and (plating electroplating).clm. and concentration. clm. and (semiconductor wafer microfeature electronic microelectronic)	US-PGPUB	OR	ON	2006/09/08 16:50